



Features

- Efficiency up to 93%
- 180 µA(TYP.) Quiescent Current
- Output Current: Up to 1A
- Internal Synchronous Rectifier
- 1.5MHz Switching Frequency
- Soft Start
- Under-Voltage Lockout
- Short LED Protection
- Open LED Protection
- Thermal Shutdown
- 5-pin Small SOT23-5 Packages
- Pb-Free Package

Applications

- 3AA or 4AA Batteries Powered Flashlight
- 1 Cell Li-Ion Battery Powered Flashlight

General Description

The PAM2804 is a step-down constant current LED driver. When the input voltage down to lower than LED forward voltage, then PAM2804 run into LDO mode.

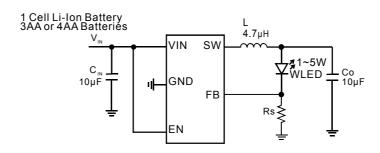
The PAM2804 supports a range of input voltages from 2.5V to 6.0V, allowing the use of a single Li+/Li-polymer cell, 3AA or 4AA cell, USB, and other standard power sources.

The FB voltage is only 0.1V to achieve high efficiency.

PAM2804 employ internal power switch and synchronous rectifier to minimize external part count and realize high efficiency.

During shutdown, the input is disconnected from the output and the shutdown current is less than $1\mu A$. Other key features include under-voltage lockout to prevent deep battery discharge of the Li+ battery.

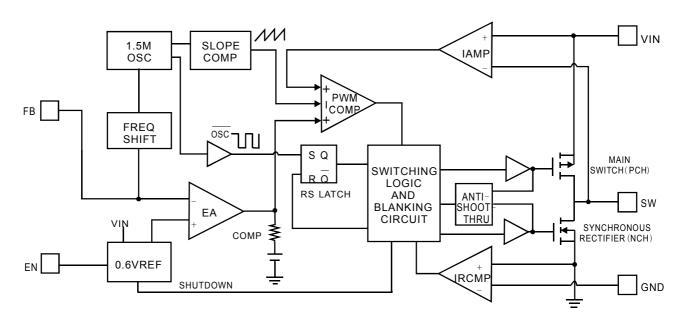
Typical Application



ILED =0.1/Rs

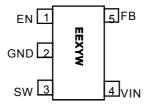


Block Diagram



Pin Configuration & Marking Information

Top View SOT23-5



EE: Product Code of PAM2804 X: Internal Code

Y: Year W: Week

Pin Description

Name	Function
VIN	Chip main power supply pin
GND	Ground
EN	Enable control input. Force this pin voltage above 1.5V, enables the chip, and below
	0.3V shuts down the device.
FB	Feedback voltage to internal error amplifier, the threshold voltage is 0.1V.
SW	The drains of the internal main and synchronous power MOSFET.





Absolute Maximum Ratings

These are stress ratings only and functional operation is not implied. Exposure to absolute maximum ratings for prolonged time periods may affect device reliability. All voltages are with respect to ground.

Input Voltage0.3V to 6.5	V Junction Temperature150°C
EN, FB Pin Voltage0.3V to V	Storage Temperature Range65°C to 150°C
SW Pin Voltage0.3V to (V _{IN} +0.3V	Soldering Temperature300°C, 5sec

Recommended Operating Conditions

Supply Voltage	2.5V to 6.0V	Junction	Temperature	Range40 °C to 125 °C
Operation Temperature Range	I0°C to 85°C			

Thermal Information

Parameter	Package	Symbol	Maximum	Unit	
Thermal Resistance	SOT23-5 ^{Note}	0	400		
(Junction to Case)	SU123-5	$\theta_{ extsf{JC}}$	130	°CW	
Thermal Resistance	00700 5	0	050	C/VV	
(Junction to Ambient)	SOT23-5	θ_{JA}	250		
Internal Power Dissipation	SOT23-5	P_{D}	400	mW	

Note:

The maximun output current for SOT23-5 package is limited by internal power dissipation capacity as described in Application Information herein after.

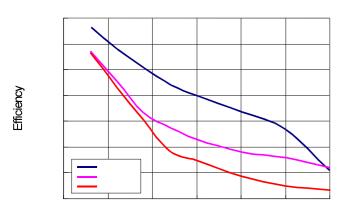


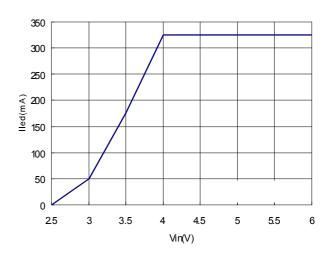
Electrical Characteristic

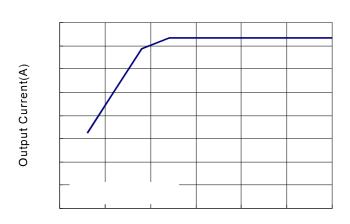
 T_A =25°C, V_{IN} =4.2V, Real WLED load, C_{IN} =10 μ F, C_{\circ} =10 μ F, L=4.7 μ H, unless otherwise noted.

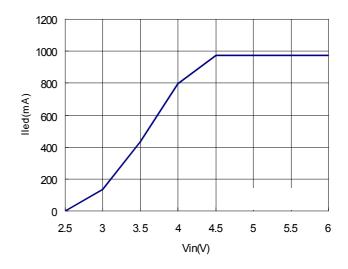
PARAMETER	SYMBOL	Test Conditions		MIN	TYP	MAX	UNITS
Input Voltage Range	V _{IN}			2.5		6.0	V
Regulated Feedback Voltage	V_{FB}			0.095	0.1	0.105	V
Peak Inductor Current	I _{PK}	V _{IN} =5V			1.5		Α
Quiescent Current	Io	No load			180		μΑ
Shutdown Current	I _{SD}	$V_{EN} = 0V$				1	μΑ
Oscillator Frequency	f _{osc}	V _O = 100%		1.2	1.5	1.8	MHz
			P MOSFET		0.3	0.45	Ω
Drain-Source On-State Resistance	R _{DS(ON)}	I_{DS} =100mA	N MOSFET		0.35	0.5	Ω
SW Leakage Current	I _{LSW}				±0.01	1	μA
High Efficiency	η				93		%
EN Threshold High	V _{EH}			1.5			V
EN Threshold Low	V _{EL}					0.3	V
EN Leakage Current	I _{EN}				±0.01		μA
Over Temperature Protection	ОТР				150		°C
OTP Hysteresis	ОТН				30		°C

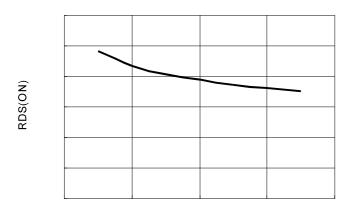
Typical Performance Characteristics T_A =25°C, C_{IN} =10 μ F, C_o =10 μ F, L=4.7 μ H, unless otherwise noted.

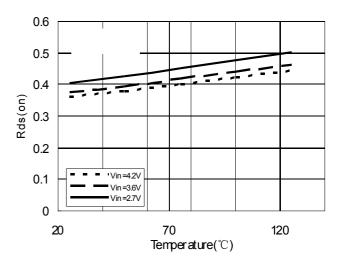










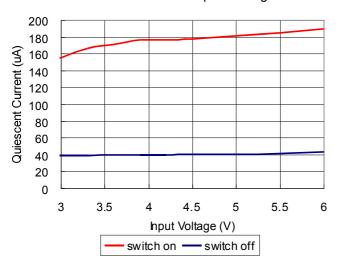


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Typical Performance Characteristics $T_A=25\,^{\circ}C,\,C_{IN}=10\mu F,\,C_{o}=10\mu F,\,L=4.7\mu H,$ unless otherwise noted.

Quiescent Current Vs Input Voltage



Start up with Enable



Power Analog Microelectronics, Inc

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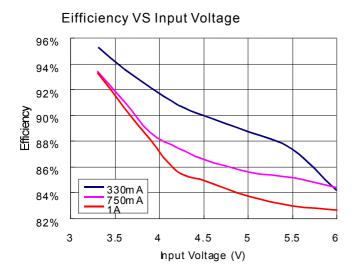
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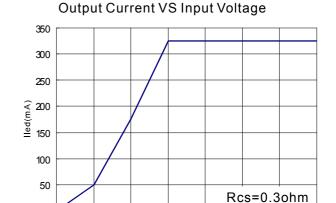
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3.5

Typical Performance Characteristics T_A = 25°C, C_{IN} = 10 μ F, C_o = 10 μ F, L=4.7 μ H, unless otherwise noted.





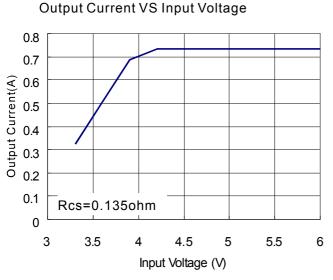
4.5

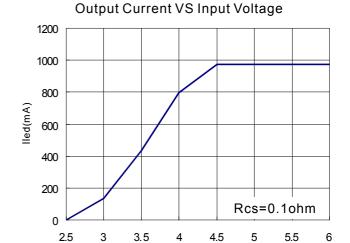
Vin(V)

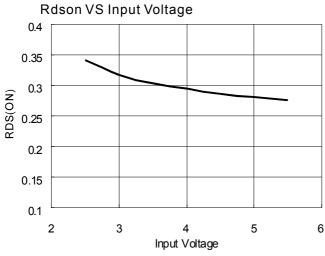
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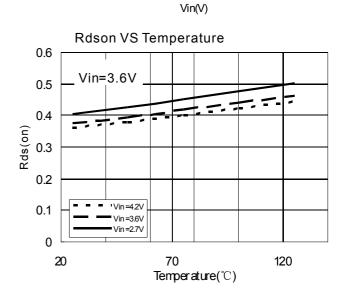
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Application Information

For the condition where the step-down converter is in dropout at 100% duty cycle, the total device dissipation reduces to:

$$P_D = I_O^2 R_{DSONH} + I_O V_{IN}$$

Since R_{DS(ON)}, quiescent current, and switching losses all vary with input voltage, the total losses should be investigated over the complete input voltage range. The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surrounding airflow and temperature difference between junction and ambient. The maximum power dissipation can be calculated by the following formula:

$$P_{D} = \frac{T_{J(MAX)} - T_{A}}{\theta_{JA}}$$

Where TJ(max) is the maximum allowable junction temperature $125^{\circ}\text{C.T}_{\text{A}}$ is the ambient temperature and θ_{JA} is the thermal resistance from the junction to the ambient. Based on the standard JEDEC for a two layers thermal test board, the thermal resistance θ_{JA} of SOT23-5 package is 250°C/W . The maximum power dissipation at $T_{\text{A}} = 25^{\circ}\text{C}$ can be calculated by following formula:

$$P_D = (125^{\circ}C - 25^{\circ}C)/250^{\circ}C/W = 0.4W$$

Setting the Output Current

The internal feedback(FB) voltage is 0.1V (Typical). The output current is calculated as below:

The output Current is given by the following table.

Rs(Ω)	ILED(mA)
0.286	350
0.143	700
0.1	1000

As the input voltage approaches the LED forward voltage, the PAM2804 turns the P-channel transistor continuously on. In this mode the Voltage drop on LED is equal to the input voltage minus the voltage drop across the P - channel transistor, Inductor and current resistor:

$$V_{IEDDROP} = V_{IN} - ILED (R_{dson} + R_I + R_S)$$

where R_{dson} = P-channel switch ON resistance, ILED = LED current, R_{L} = Inductor DC resistance, R_{s} = Inductor DC resistance.

Thermal Shutdown

When the die temperature exceeds 150°C, a reset occurs and the reset remains until the temperature decrease to 120°C, at which time the circuit can be restarted.

100% Duty Cycle Operation





Application Information

PCB Layout Check List

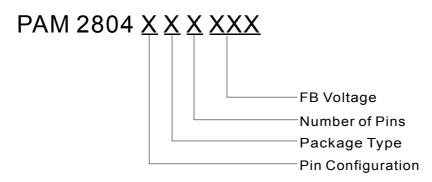
When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the PAM2804. These items are also illustrated graphically in Figure 1. Check the following in your layout:

- 1. The power traces, consisting of the GND trace, the SW trace and the VIN trace should be kept short, direct and wide.
- 2. Does the V_{FB} pin connect directly to the current sense resistor? The current sense resistor to GND trace should be kept short, direct and wide.
- 3. Does the (+) plate of CIN connect to VIN as closely as possible? This capacitor provides the AC current to the internal power MOSFETs.
- 4. Keep the switching node, SW, away from the sensitive VFB node.
- 5. Keep the (–) plates of C_{IN} and C_{OUT} as close as possible.

Tel:0755-82536500



Ordering Information

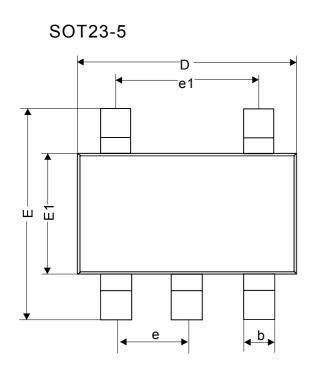


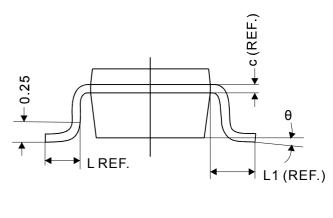
Pin Configuration	Package Type	Number of Pins	FB Voltage
A Type	A: SOT-23	B: 5	010: 0.1V
1. EN			
2. GND			
3. SW			
4. VIN			
5. FB			

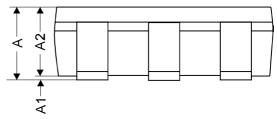
Part Number	Marking	Package Type	Standard Package
PAM2804AAB010	Refer to P2	SOT-23-5	3,000Units/Tape&Reel



Outline Dimensions







DEE	Millimeter		
REF.	Min	Max	
Α	1.101	/AX	
A1	0	0.10	
A2	0.70	1	
С	0.12REF.		
D	2.70	3.10	
Е	2.60	3.00	
E1	1.40	1.80	
L	0.45 REF.		
L1	0.60 REF.		
θ	0°	10°	
b	0.30	0.50	
е	0.95 REF.		
e1	1.90 REF.		